



SCN400

IEC61850-3, IEEE-1613 2U
FANLESS SUBSTATION



POWER AUTOMATION COMPUTER

- Intel 9th. Core i9-10900TE Processor
- 2xDDR4 up to 64GB
- 4 x LAN (RJ45), 2 x COM (DB9) , 6 x USB, 2 x DP, 1 x VGA, 1 x DVI-D
- 2 x 2.5" Easy swap SSD/HDD Tray (RAID 0/1)
- 2 x PCIE Expansion Slots
- Trusted Platform Module

Specifications

SYSTEM

CPU	10th Generation Intel® Core™ i9/i7/i5 Processors Intel® Core™ i9-10900TE(20M Cache, up to 4.60 GHz) Intel® Core™ i7-10700TE(16M Cache, up to 4.50 GHz) Intel® Core™ i5-10500TE(12M Cache, up to 3.70 GHz)
Memory type	2 x DDR4 up to 64GB
Expansion Slot	2 x IO Expansion Slots 1 x MXM 3.1 Slot
Storage Device	4 x 2.5" Easy swap HDD/SSD Tray

REAR I/O

Power Button	1 with backlight
Indicator	1 HDD backlight
USB	2 x USB 2.0

FRONT I/O

Power Input	24V DC-IN
LAN	4 x RJ45 LAN
USB	4 x USB 3.0
Display	2 x DP 1 x DVI-D
VGA	1 x VGA

OPTIONAL

Serial Ports	2 x COM ports ((2 x RS232/422/485, 4 x RS232)
DIO	16-bit (8 in/8 out)
48V DC Input	48V DC Input
NVIDIA GPU Module	NVIDIA 1050Ti / RTX2060 GPU
Dual 10GbE Module	INTEL X710 Dual 10GbE
Redundant Power	220VAC/DC Redundant Power Supply

OS SUPPORT LIST

Windows	Windows 8.1 x32/ x64 、 Windows 10 x32/ x64
Linux	Fedora 15, Ubuntu, Red Hat
Power Requirement	Wide Range 90~260V AC-in
Dimension	430 x 396 x 88 mm (W x D x H)
Operating Temp.	-20 to 60°C
Storage Temp.	-40°C to 85°C
Relative Humidity	5% to 95%, non-condensing
Certification	CE, FCC, MIL-STD 810G Compliance
System Design	Fanless
Mounting	2U Rackmount
MIL-STD-810G Test	Method 507.5, Procedure II (Temperature & Humidity) Method 516.6 Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6 Shock-Procedure I Operating (Mechanical Shock) Method 514.6 Vibration Category 24/Non-Operating (Category 20 & 24, Vibration) Method 514.6 Vibration Category 20/Operating (Category 20 & 24, Vibration) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock)
EMC	CE, FCC compliant
Green Product	RoHS, WEEE compliance

Ordering Information

SCH400

2U 19" Power Automation Fanless Server Computer with Intel. 10th gen Core i7 Processor, 4x RJ45, 2x COM ports, 'Wide range 90~260V AC-in, Operating Temperature -20~+60°C

SCH400-GW

2U 19" Power Automation Fanless Server Computer with Intel. 6th gen Core i7 Processor, NVIDIA 1050Ti / 1080 GPU, 8x RJ45, 6 x COM ports, 1 x 16-bit DIO, INTEL X710 Dual 10GbE, 48V DC Input, 220VAC/DC Redundant Power Supply, Operating Temperature -20~+60°C

Dimension

